

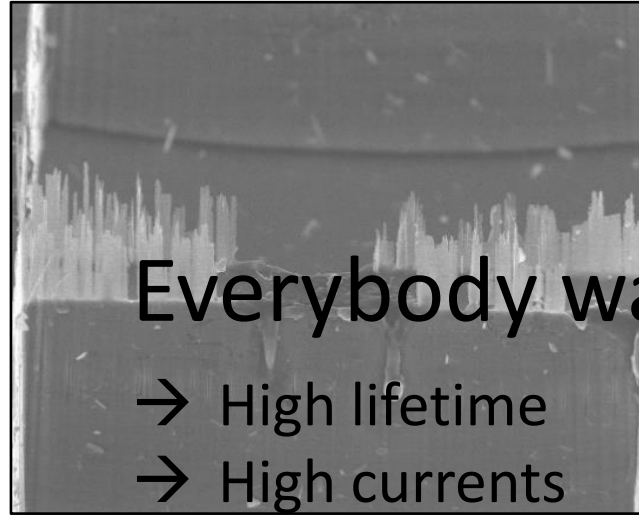
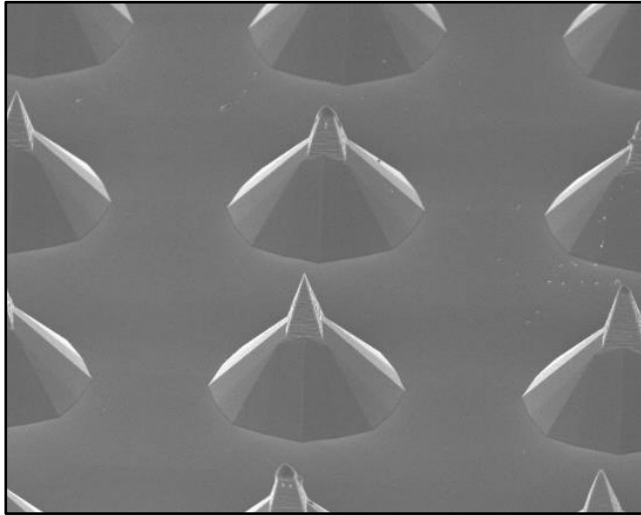


## Current dependent field emission performance test using a CMOS imaging sensor

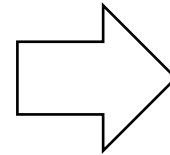
8<sup>th</sup> ITG IVEW

Simon Edler, Andreas Schels, Florian Herdl, Walter Hansch, Michael Bachmann,  
Dominik Wohlfartsstätter, Felix Düsberg, Andreas Pahlke, Matthias Hausladen,  
Philipp Buchner, Rupert Schreiner

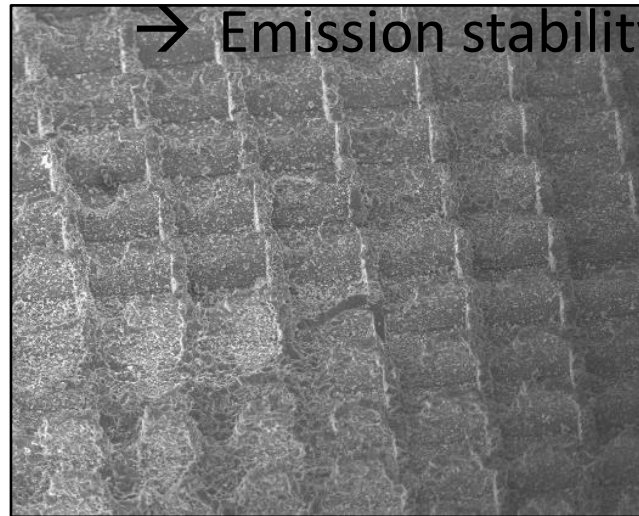
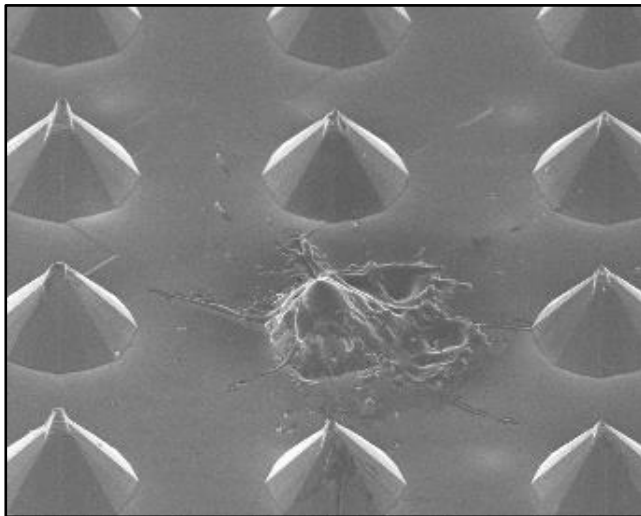
Everybody gets:



- High lifetime
- High currents
- Emission stability

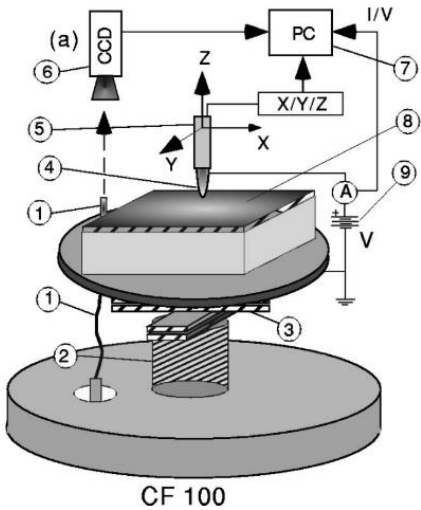


**Need for Homogeneous current distribution**

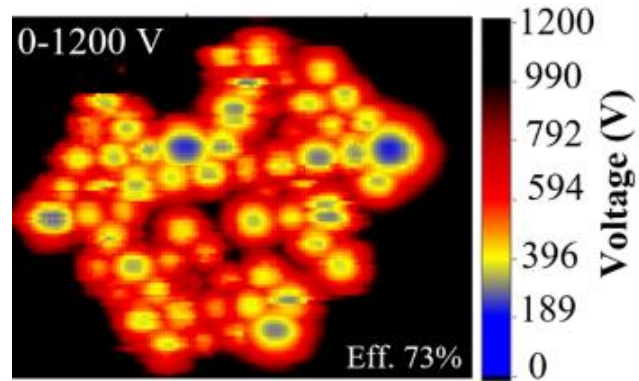


- Field emission scanning microscope

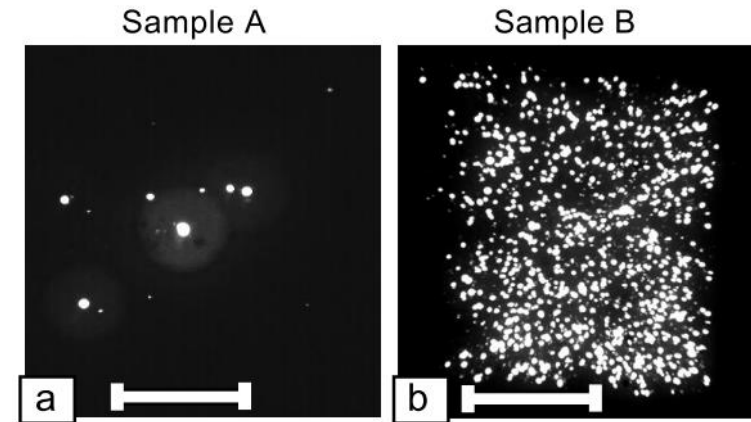
- Phosphor screen



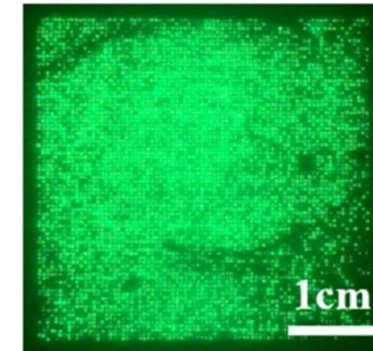
J. Vac. Sci. Technol. B  
Microelectron. Nanom. Struct.  
**20**, 326 (2002)



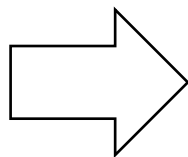
Rev. Sci. Instrum. **91**, 083906 (2020)



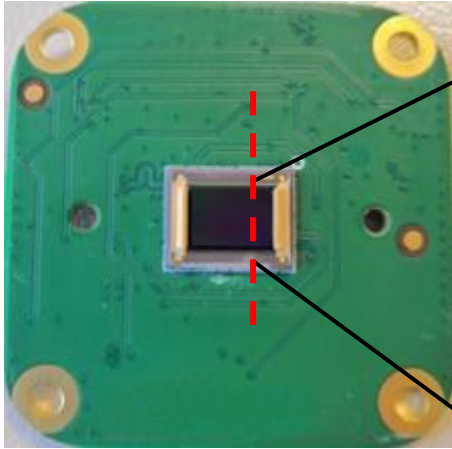
J. Appl. Phys. **90**, 768 (2001).



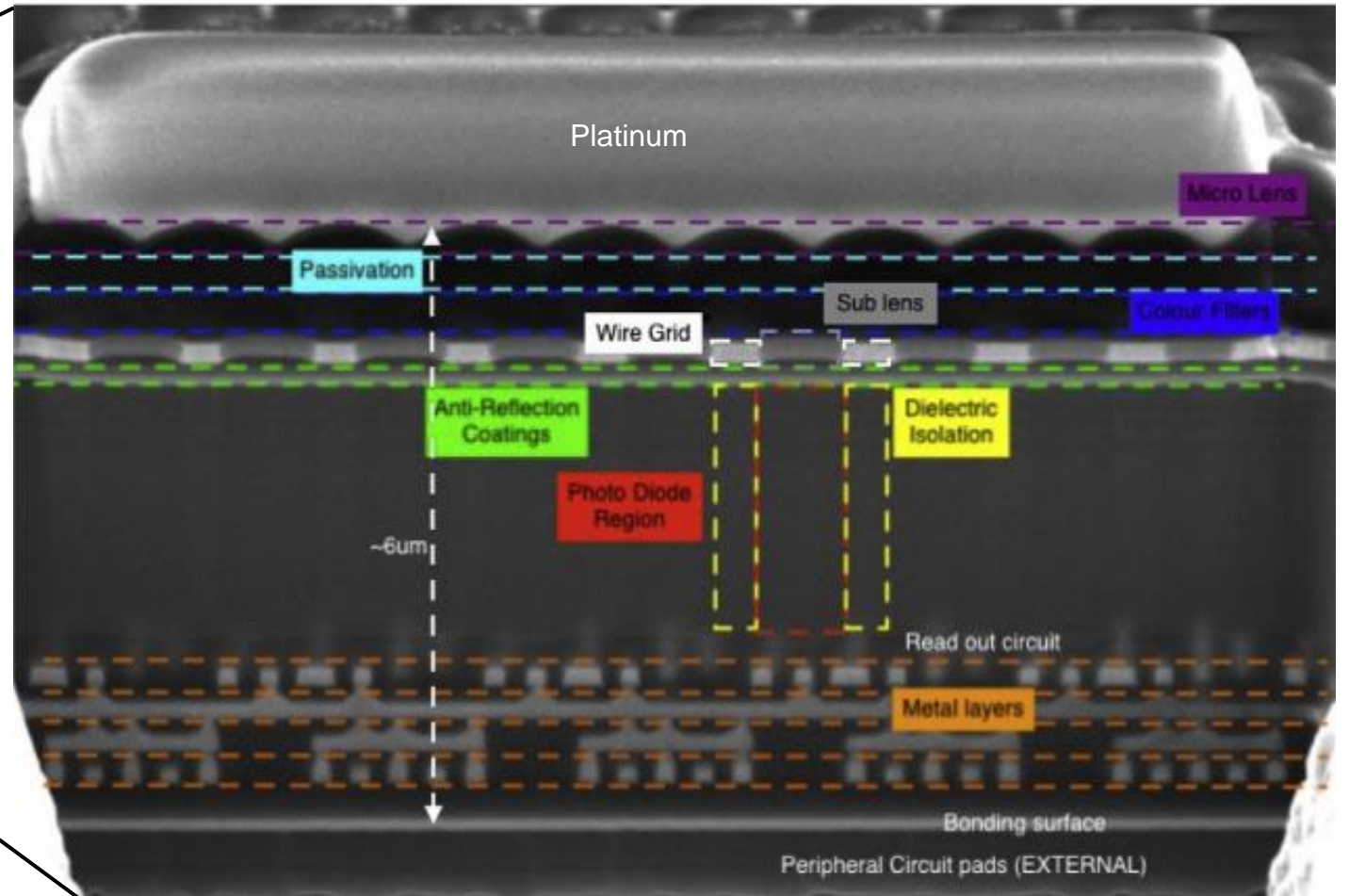
Sci. Rep. **8**, 12294 (2018).



**Expensive and limited**



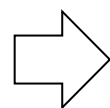
$\sim 1 - 1.5 \mu\text{m}$



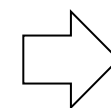
Forensic Sci. Int. Digit. Investig. **32**, 200900 (2020)

## → Raspberry Pi HQ Camera:

- Costs approx. 50 USD
- Easy to integrate
- Reasonable resolution
- High dynamic range
- Easily controllable



**Electrons don't pass the top layers**



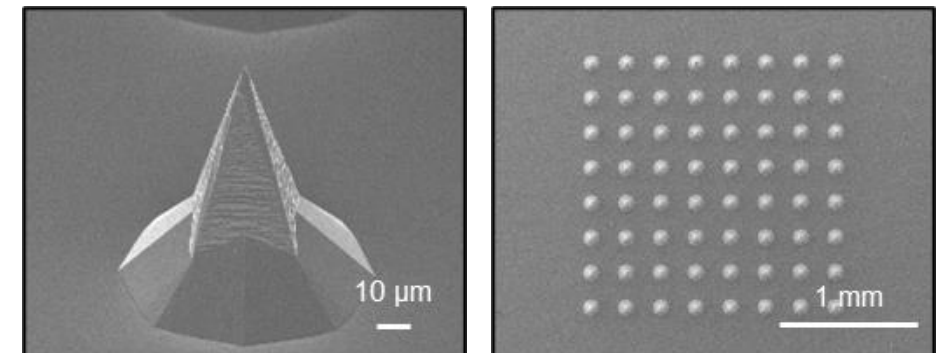
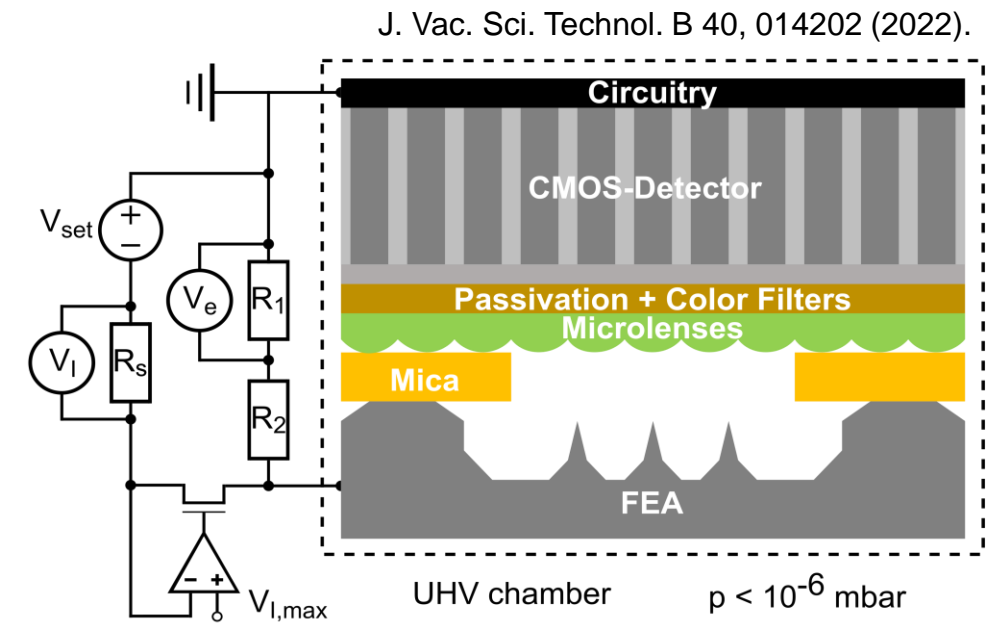
**X-ray detection**

- Measurement Setup

- Camera connected to ground
- Mica sheet for insulation (approx. 30  $\mu\text{m}$ )
- FEA at up to  $-1.1\text{ kV}$
- Regulation circuit for constant current measurements
- $p < 10^{-6}\text{ mbar}$

- Samples

- Wafer diced and TMAH etched silicon FEAs
- 2 types:
  - 8x8-Array: tip height of 100  $\mu\text{m}$ , pitch of 250  $\mu\text{m}$
  - 20x20 Array: tip height of 50  $\mu\text{m}$ , pitch of 110  $\mu\text{m}$
- Different doping



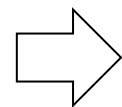
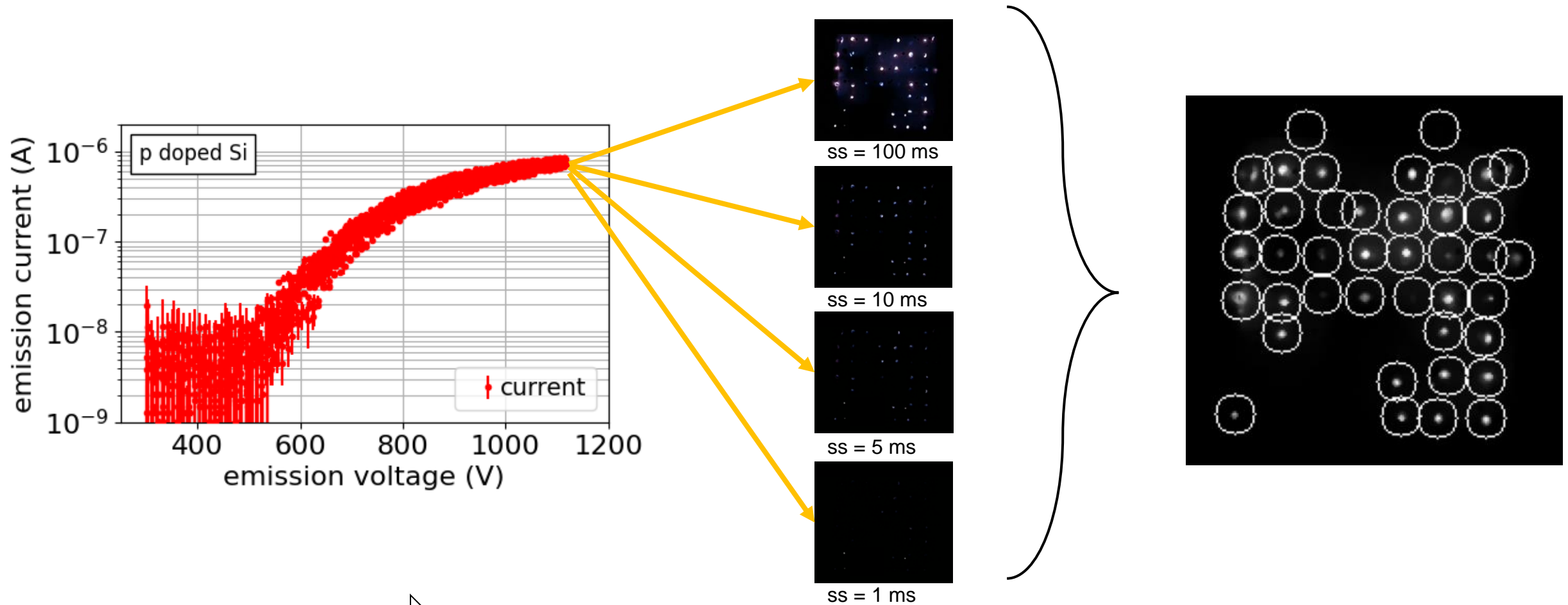
IV characteristics  
(2 measurements/voltage)

+

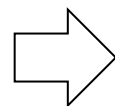
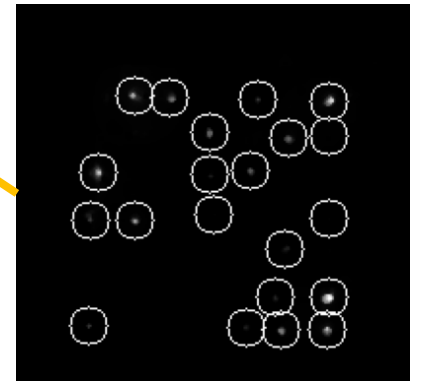
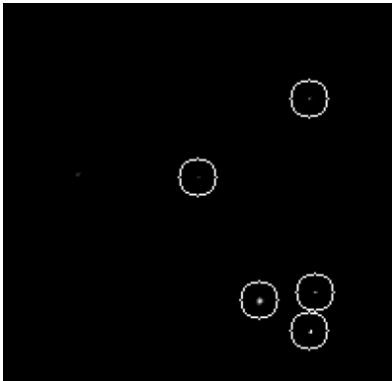
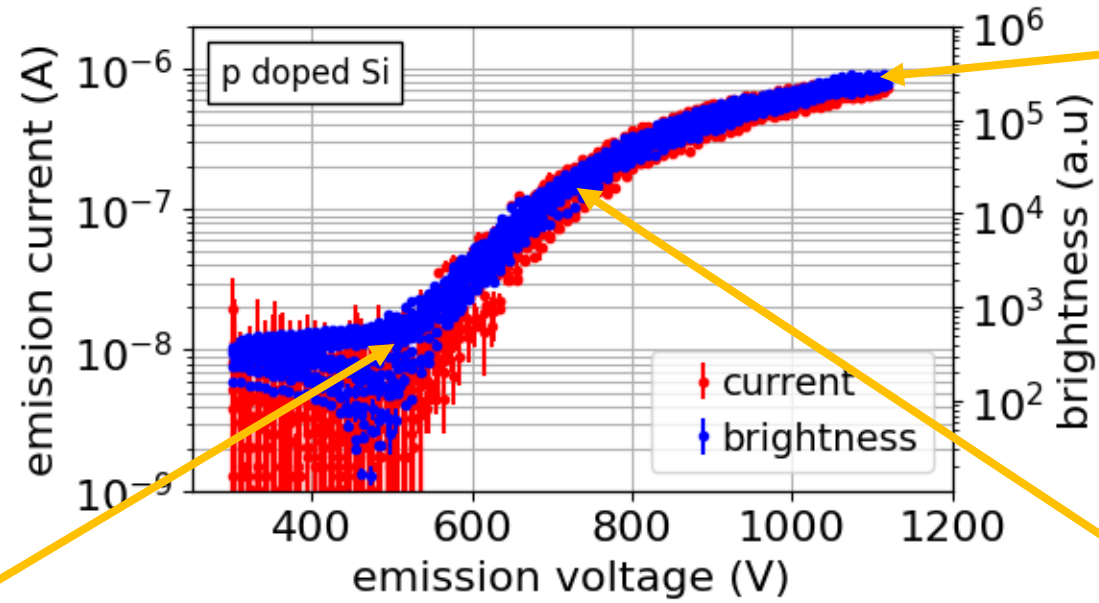
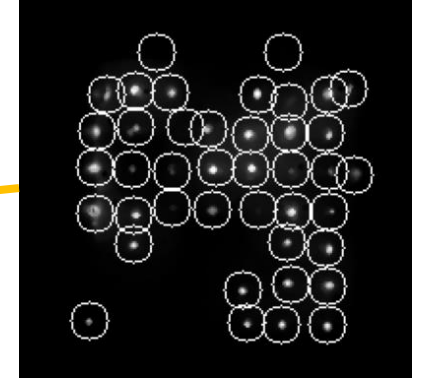
PiCam images  
(4 different shutter speeds)

=

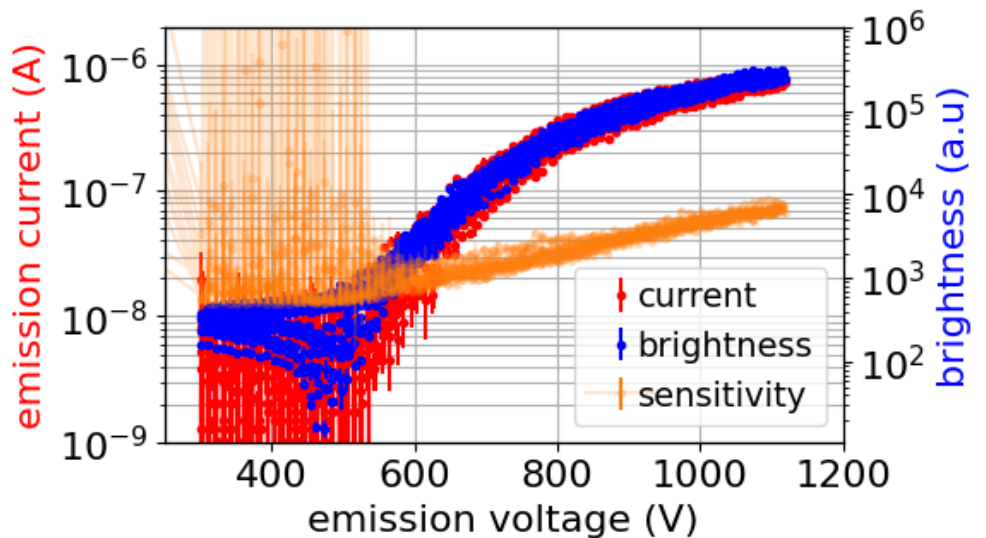
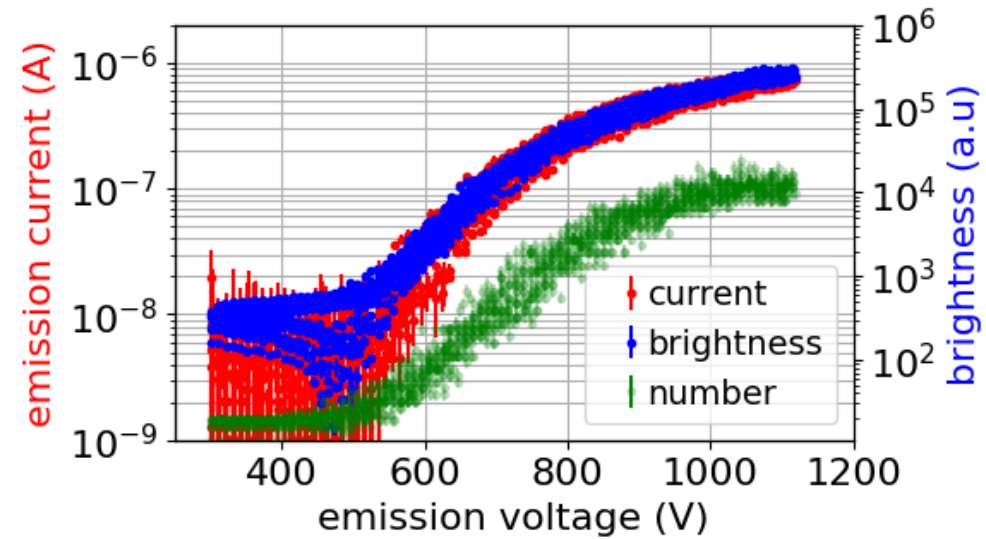
Extrapolated Image  
(1 per voltage)



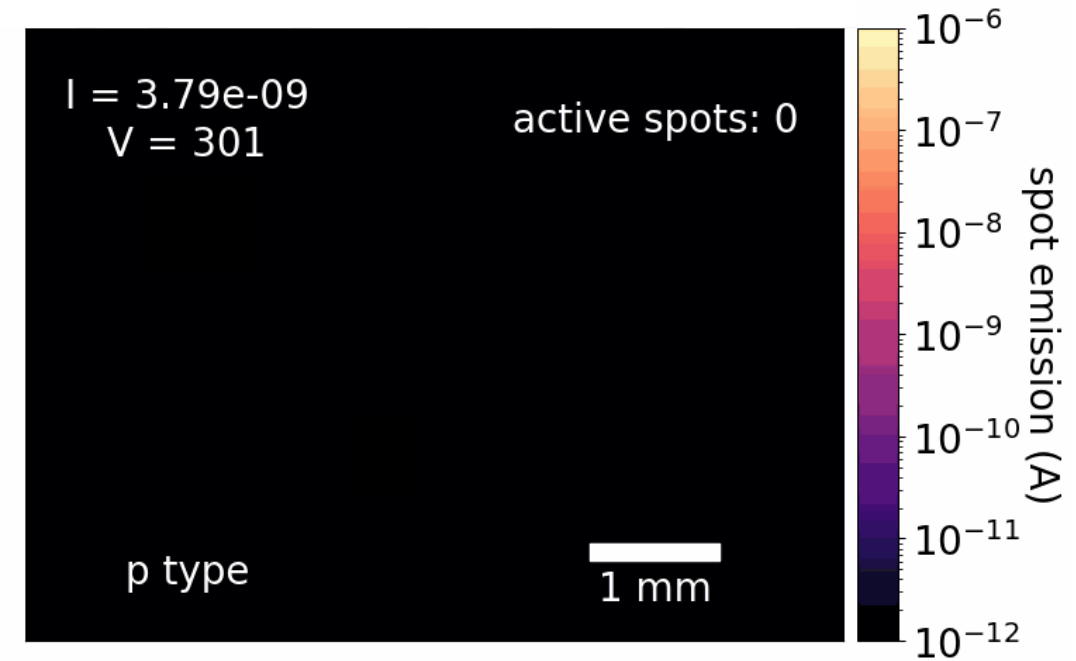
**Different shutter speeds to enhance dynamic range**



Brightness per emitter tip + integral brightness



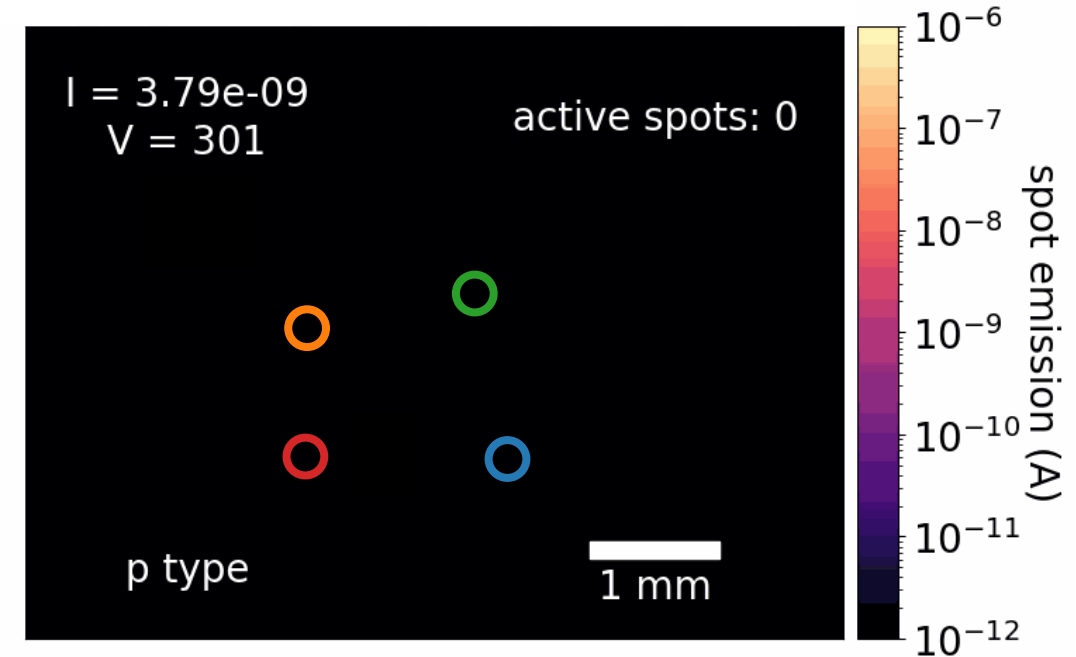
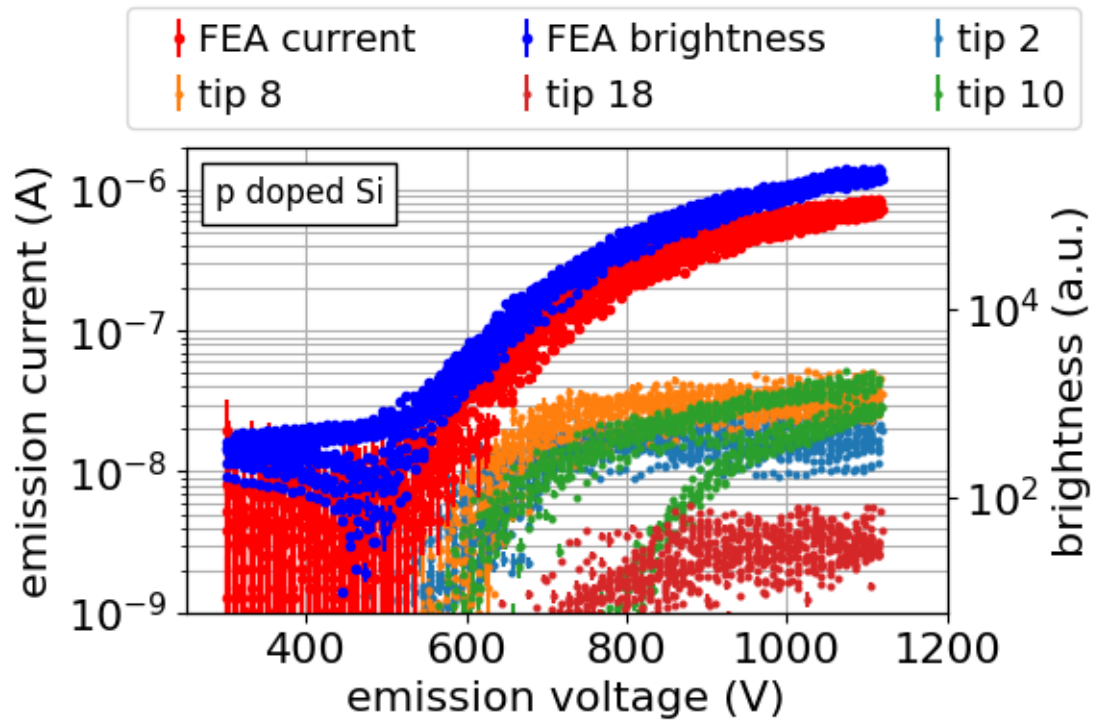
Single Spot Emission Heatmap



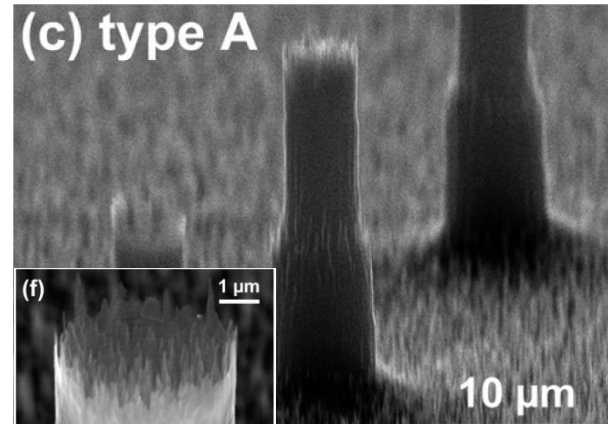
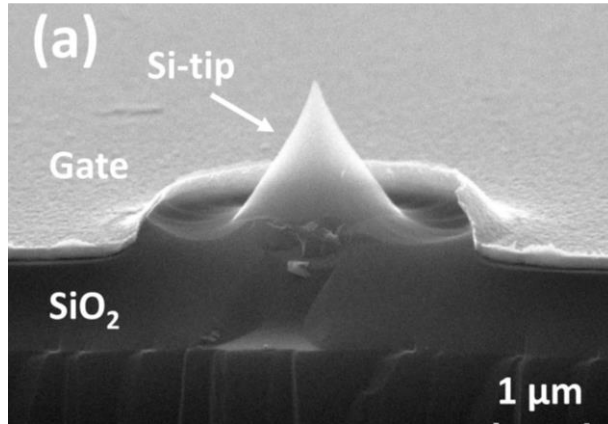
IV + BV characteristics



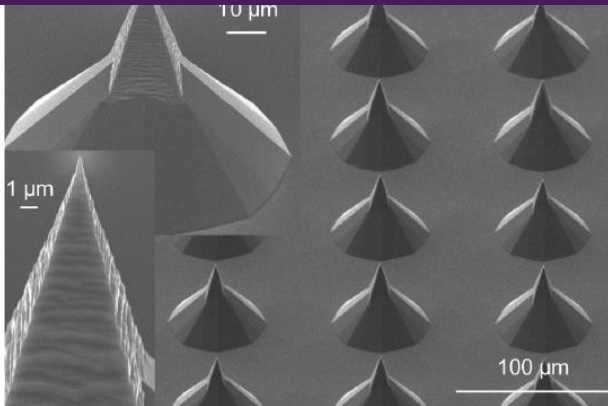
single tip characteristics



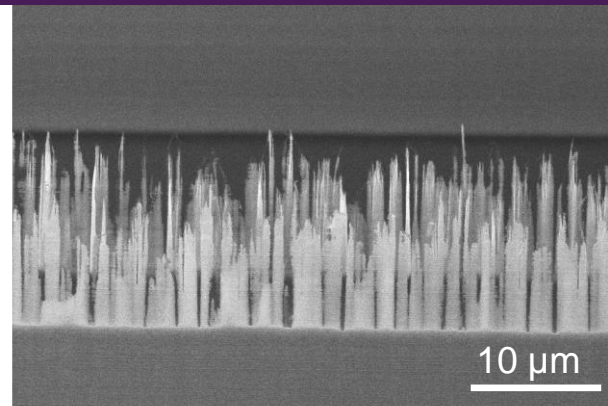
## Motivation



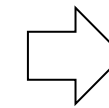
What is the best emitting structure?



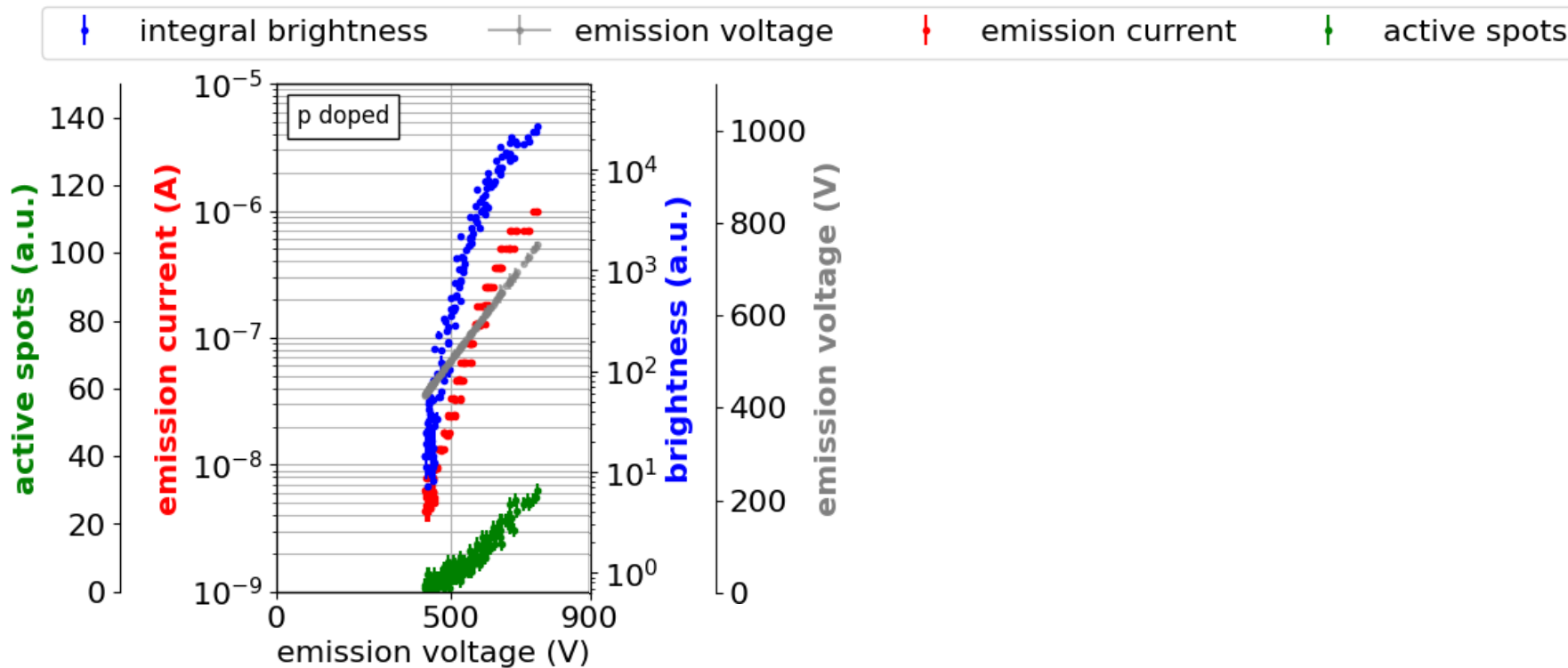
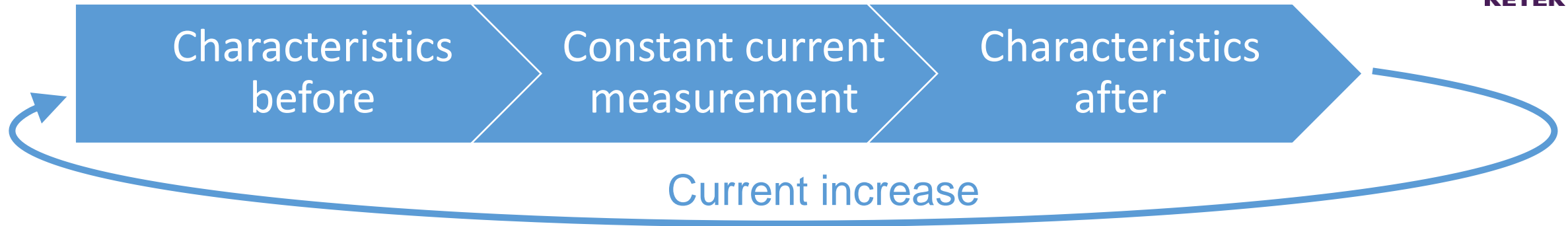
J. Vac. Sci. Technol. B 39, 013201 (2021)



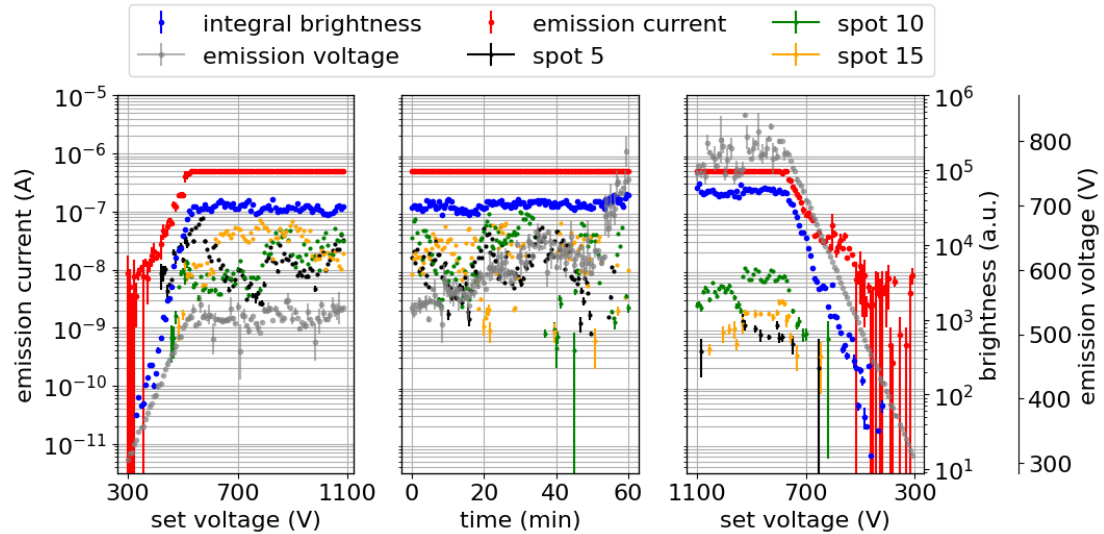
J. Vac. Sci. Technol. B **40**, 010605 (2022)



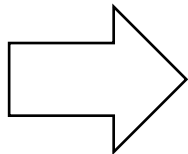
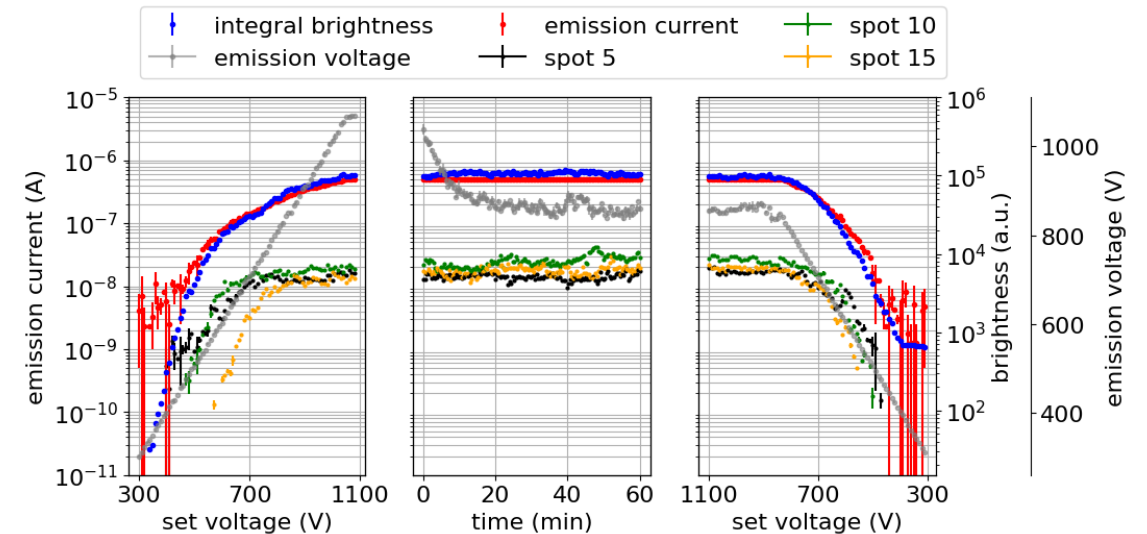
Just characteristics  
don't allow good comparison



## n-type Si

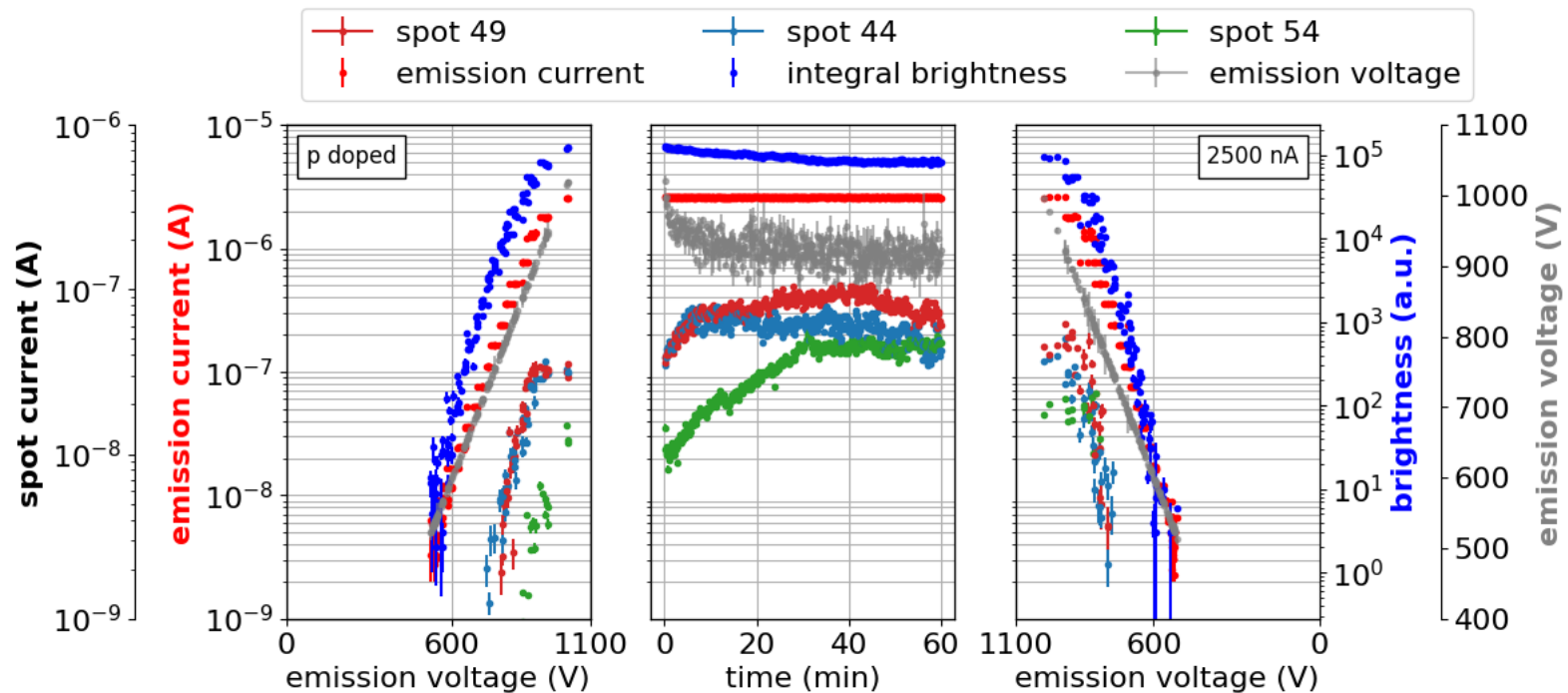


## p-type Si



**Homogenization via doping  
now observable**

- Increase of single tip saturation level during CCM:
  - Increased charge carrier generation



- Integral measurement of field emission
- High dynamic range by different shutter speeds
- Emission current and characteristics of single tips
- Homogenisation of field emission by p-doping

# Questions?

- Comparison of SEM pictures before and after CDPT
- Triode setup
- Comparison of different types of FEAs